MOSFETs Silicon P-Channel MOS

SSM6J825R

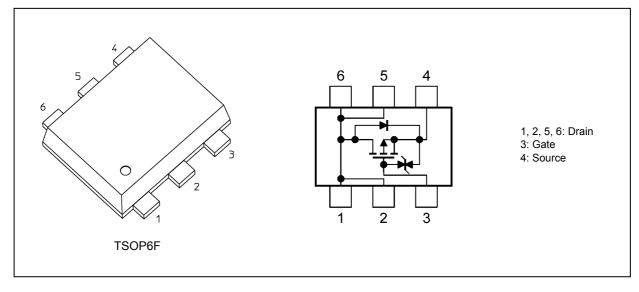
1. Applications

Power Management Switches

2. Features

- (1) 4.0-V drive
- (2) Low drain-source on-resistance
 - $\begin{array}{l} : {\rm R}_{\rm DS(ON)} = 86 \ {\rm m}\Omega \ ({\rm max}) \ (@{\rm V}_{\rm GS} = -4.0 \ {\rm V}) \\ {\rm R}_{\rm DS(ON)} = 73 \ {\rm m}\Omega \ ({\rm max}) \ (@{\rm V}_{\rm GS} = -4.5 \ {\rm V}) \\ {\rm R}_{\rm DS(ON)} = 45 \ {\rm m}\Omega \ ({\rm max}) \ (@{\rm V}_{\rm GS} = -10 \ {\rm V}) \end{array}$

3. Packaging and Pin Assignment



4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25$ °C)

Characteristics				Symbol	Rating	Unit
Drain-source voltage				V _{DSS}	-30	V
Gate-source voltage				V _{GSS}	-20 / +10	
Drain current (DC)			(Note 1)	Ι _D	-4	A
Drain current (pulsed)			(Note 1), (Note 2)	I _{DP}	-12	
Power dissipation			(Note 3)	PD	1.5	w
Power dissipation		t ≤ 10 s	(Note 3)	PD	3]
Channel temperature				T _{ch}	150	°C
Storage temperature				T _{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Ensure that the channel temperature does not exceed 150 °C.
- Note 2: Repetitive rating; pulse width limited by maximum channel temperature.
- Note 3: Device mounted on an 25.4 mm × 25.4 mm × 1.6 mm FR4 glass epoxy board (Cu pad: 645 mm²)
- Note: This transistor is sensitive to electrostatic discharge and should be handled with care.
- Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.
- Note: The channel-to-ambient thermal resistance, R_{th(ch-a)}, and the drain power dissipation, P_D, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

5. Electrical Characteristics

5.1. Static Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V _{DS} = 0 V, V _{GS} = -16/+10 V	_	_	±1	μA
Drain cut-off current		I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V	_		-1	1
Drain-source breakdown voltage		V _{(BR)DSS}	I _D = -250 μA, V _{GS} = 0 V	-30	_	_	V
Drain-source breakdown voltage		V _{(BR)DSX}	I _D = -250 μA, V _{GS} = 10 V	-20	_	_]
Gate threshold voltage		V _{th}	V _{DS} = 10 V, I _D = -250 μA	-0.9	_	-2.0	V
Drain-source on-resistance	(Note 1)	R _{DS(ON)}	I _D = -1.0 A, V _{GS} = -4.0 V	—	61	86	mΩ
			I _D = -4.0 A, V _{GS} = -4.5 V	_	55	73]
		R _{DS(ON)}	I _D = -4.0 A, V _{GS} = -10 V	_	35	45	mΩ
Forward transfer admittance	(Note 1)	Y _{fs}	V _{DS} = -10 V, I _D = -2.0 A	_	7.1	_	s

Note 1: Pulse measurement.

5.2. Dynamic Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V,	_	492	_	pF
Reverse transfer capacitance	C _{rss}	f = 1 MHz	_	75	_]
Output capacitance	C _{oss}		_	97	_]
Switching time (turn-on time)	t _{on}	V _{DS} = -15 V, I _D = -2 A,	_	49	_	ns
Switching time (turn-off time)	t _{off}	V_{GS} = 0 to -4.5 V, R_{G} = 10 Ω		80	_]

5.3. Switching Time Test Circuit

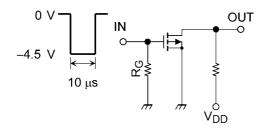


Fig. 5.3.1 Switching Time Test Circuit

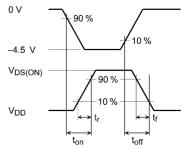


Fig. 5.3.2 Input Waveform/Output Waveform

5.4. Gate Charge Characteristics (Unless otherwise specified, T_a = 25 °C)

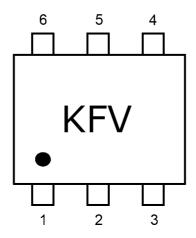
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)		V _{DD} = -15 V, I _D = -4.0 A,	_	6.2	_	nC
Gate-source charge 1	Q _{gs1}	V _{GS} = -4.5 V	_	1.5	—	
Gate-drain charge	Q _{gd}		_	2.8	_	

5.5. Source-Drain Characteristics (Unless otherwise specified, $T_a = 25$ °C)

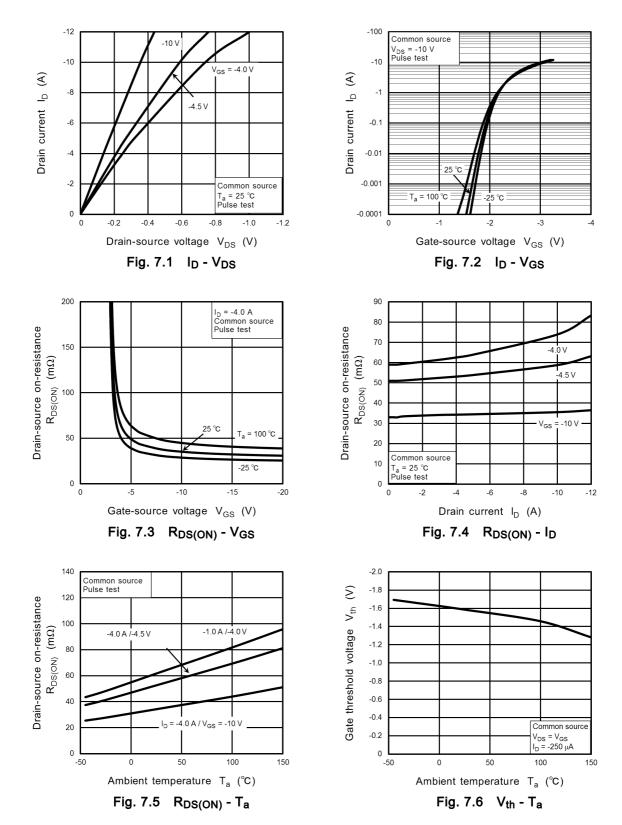
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	(Note 1)	V _{DSF}	I_{D} = 4.0 A, V_{GS} = 0 V		0.85	1.1	V

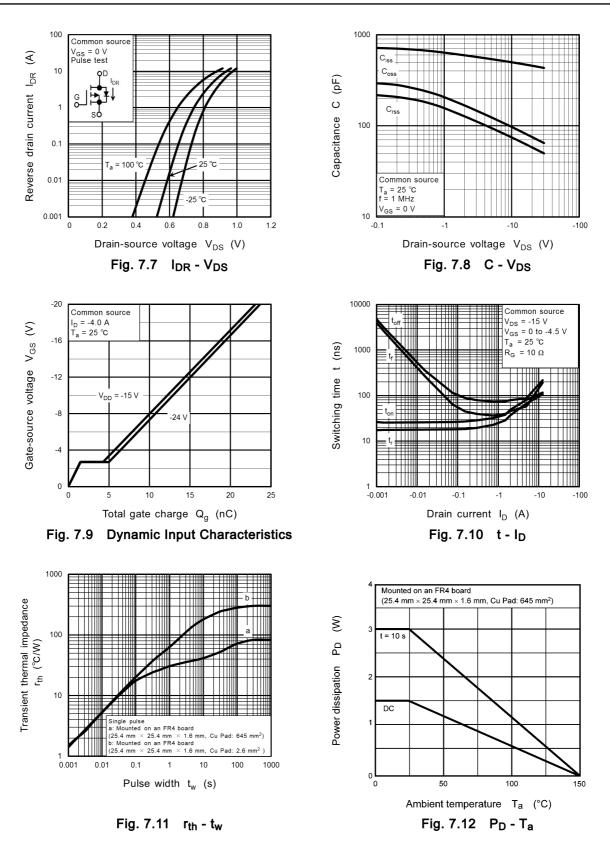
Note 1: Pulse measurement.

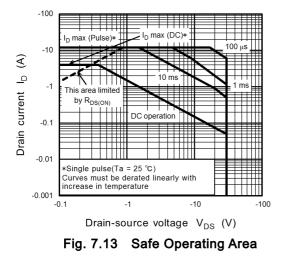
6. Marking



7. Characteristics Curves (Note)







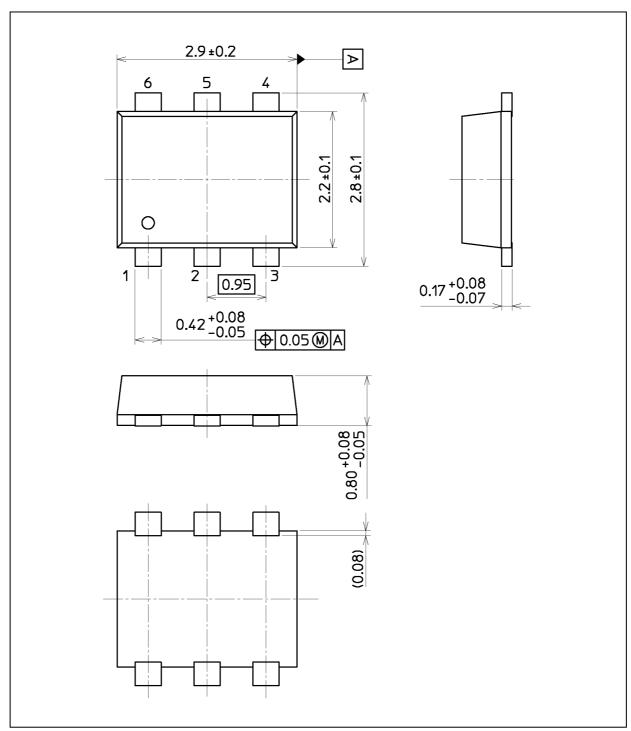
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



SSM6J825R

Package Dimensions

Unit: mm



Weight: 0.016 g (typ.)

Package Name(s) Nickname: TSOP6F

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